



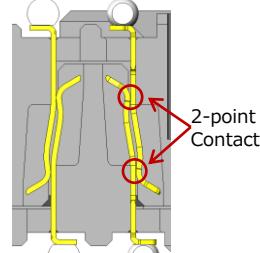
Features

- 1 **Molex "Mirror Mezz" Licensed Second Source**
- 2 **High Speed Transmission (56+Gbps NRZ / 112+Gbps PAM4)**
- 3 **OAM Specified Connector**
- 4 **High Pin Count, High Density : 688pos. (172DPs/in²)**
- 5 **Hermaphroditic Connector**
- 6 **Stub-less 2-point Contact Design**
- 7 **Protective Housing that Encapsulates the Contact Tips Prevents Warping During Mating**



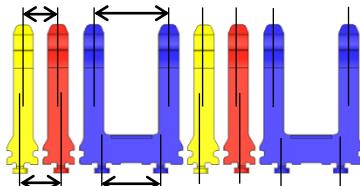
Contact Design

Stub-less Design



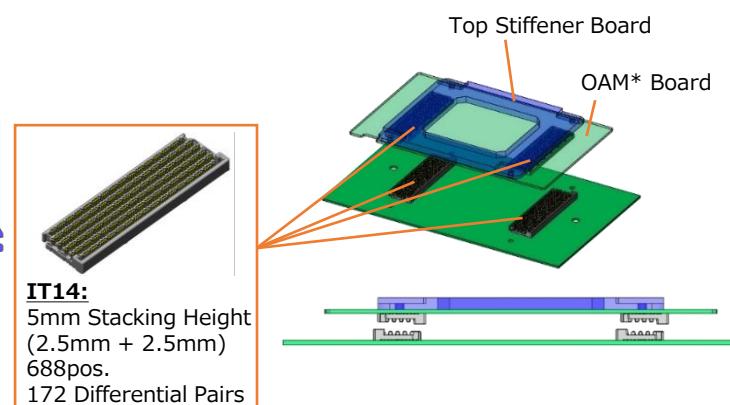
- Superior SI Performance
- 2-point Contact for Enhanced Reliability
- Wiping Amount : 1.5mm Max.

Impedance Matching (92Ω Target)



Pitch differs from contact portion and mounted portion for impedance optimization.

Used in OAM* (OCP Accelerator Module)



Specifications

Rated Current	1.2A
Rated Voltage	30V AC/DC
Operating Temperature	-55 to +105°C
Contact Resistance*	30mΩ Max.
Withstanding Voltage	500V DC for 1min.
Insulation Resistance	1000MΩ (500V DC)
Mating Durability	100 times
Impedance	92Ω

*Includes conductor resistance.

-Cross mates with Molex's Mirror Mezz.

-No. of Pos. : 688pos.

*OAM = OCP (Open Computer Project) Accelerator Module